



QUANTUM EFFICIENCY MEASUREMENTS OF Mg FILMS
PRODUCED BY PULSED LASER ABLATION DEPOSITION
FOR HIGH BRIGHTNESS ELECTRON SOURCES*

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NOWADAYS SITUATION IN PHOTOCATHODES

QE vs. ROBUSTNESS

LOOKING FOR
COMPROMISES
e.g. DIAMOND
SEC. EMISSION

**METALS ARE RUGGED
AND OFFER FASTEST
RESPONSE (BLOW OUT?)**

**BEST QE PERFORMANCE IN METAL
PC REACHED BY Mg (UP TO 10^{-3} $\lambda=266\text{nm}$)**

PROBLEMS

**Mg ADHERENCE ON SUBSTRATE (Cu) IN RF-GUN
ENVIRONMENT, DARK CURRENT (HIGH FIELD)**



OUR GOALS ON Mg FILMS

**SYNTHETIZE A Mg PC
TO WORK IN A RF-GUN**



FEATURES

- $QE > 10^{-4}$
- SURFACE QUALITY (EMISSION DISTRIBUTION)
- LASER RADIATION RESISTANT
- HIGH FIELD RESISTANT (LOW DARK CURRENT)
- RUGGEDNESS (SUBSTRATE ADHERENCE)

ACTIVITIES

**WORKING ON
VARIOUS LINES**

SPUTTERING

MEASUREMENTS TO
EVALUATE THIS WELL KNOWN
TECHNIQUE & MAKE IMPROVEMENTS
(VACUUM ARC DEPOSITION)

- RESISTANT FILMS (POLLUTION & LASER)
- BEST QE RESULTS UP TO NOW (BNL)
- POOR ADHERENCE

PLAD

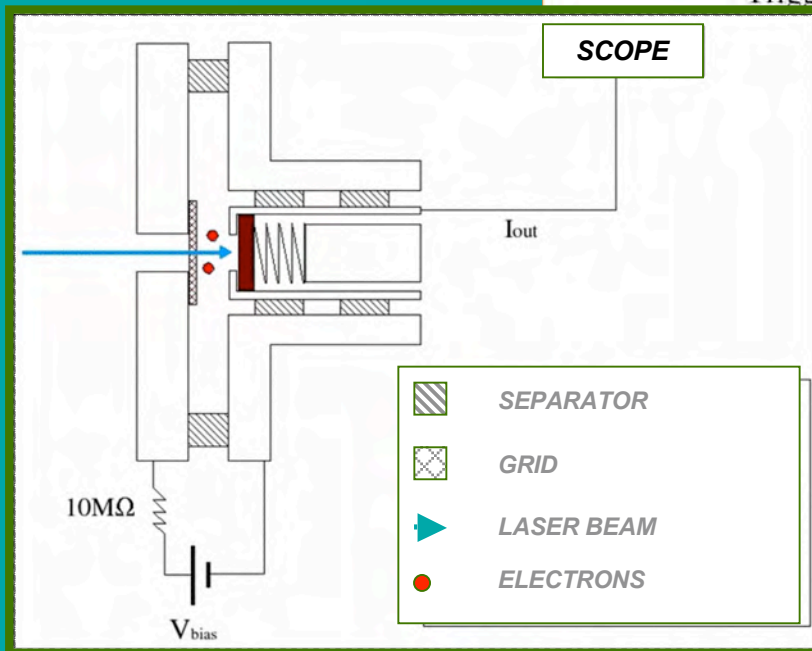
STUDYING & DEVELOPING
NEW PC AND PROTECTIVE
LAYERS BASED ON THIS
PROMISING TECHNIQUE

- GOOD FILM QUALITY
- GOOD ADHERENCE
- MULTI LAYERS
- DIFFICULT TO REACH BIG THICKNESS
- PRESENCE OF DROPLETS
- THICKNESS CONTROL

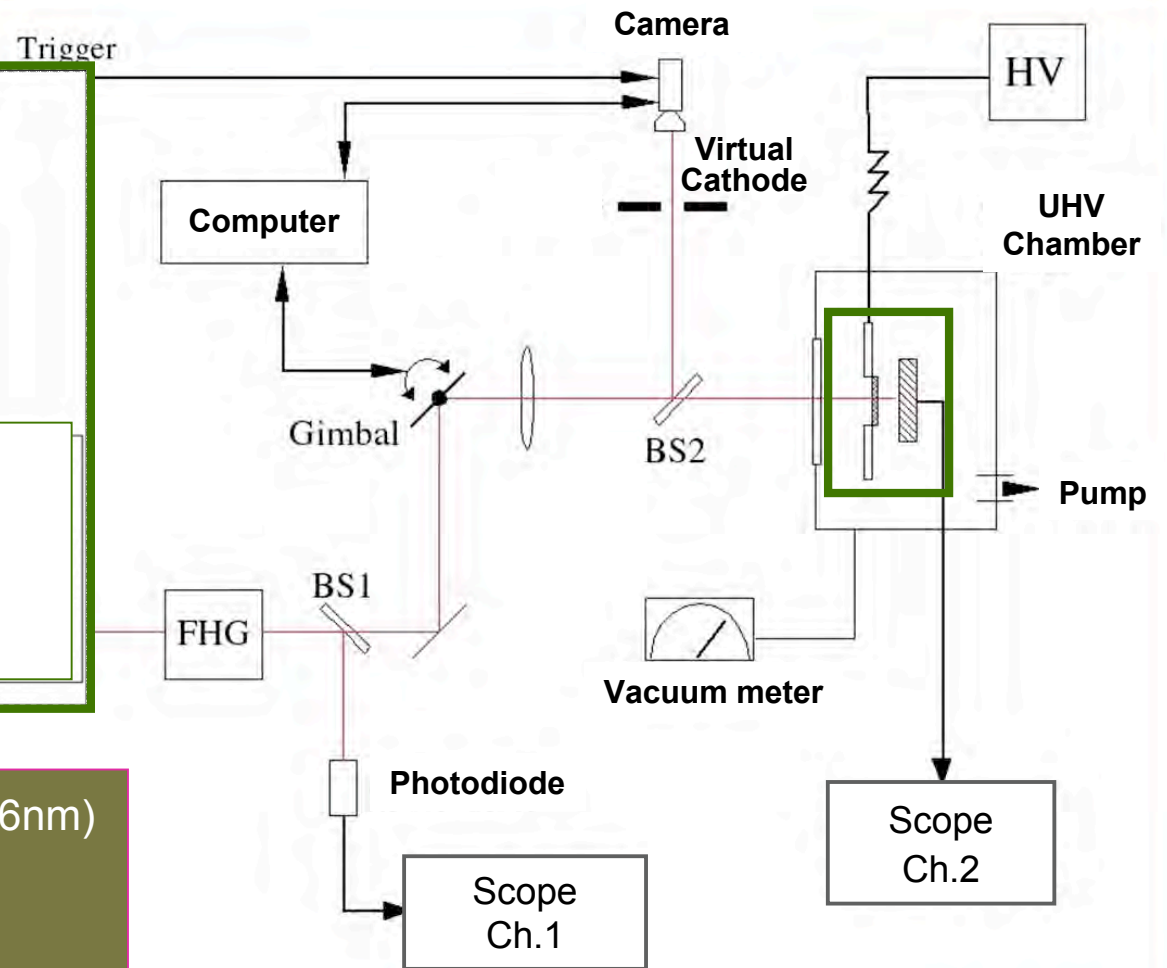


QE MEASUREMENT SET-UP

CATHODE HOLDER



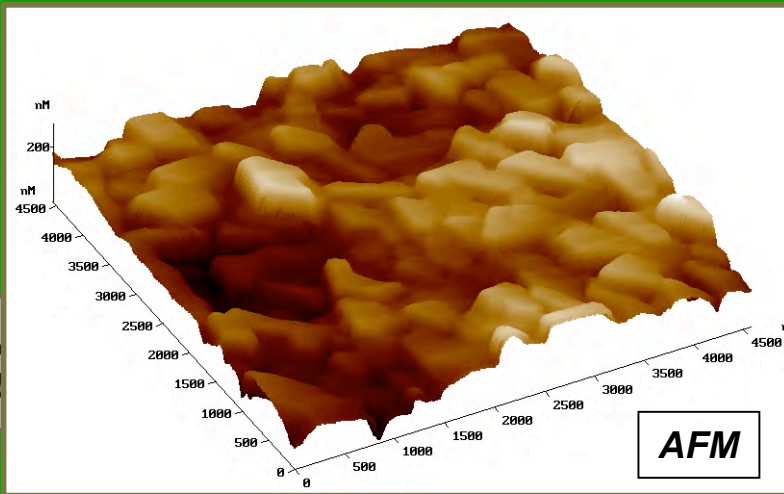
Quadrupled Nd:Yag (266nm)
 $P < 10^{-8}$ mbar
Normal Incidence
 E_{extrac} Up To 1MV/m



SPUTTERING RESULTS

10 μ m Sputtered Mg Film On Cu Substrate (Koral Labs)

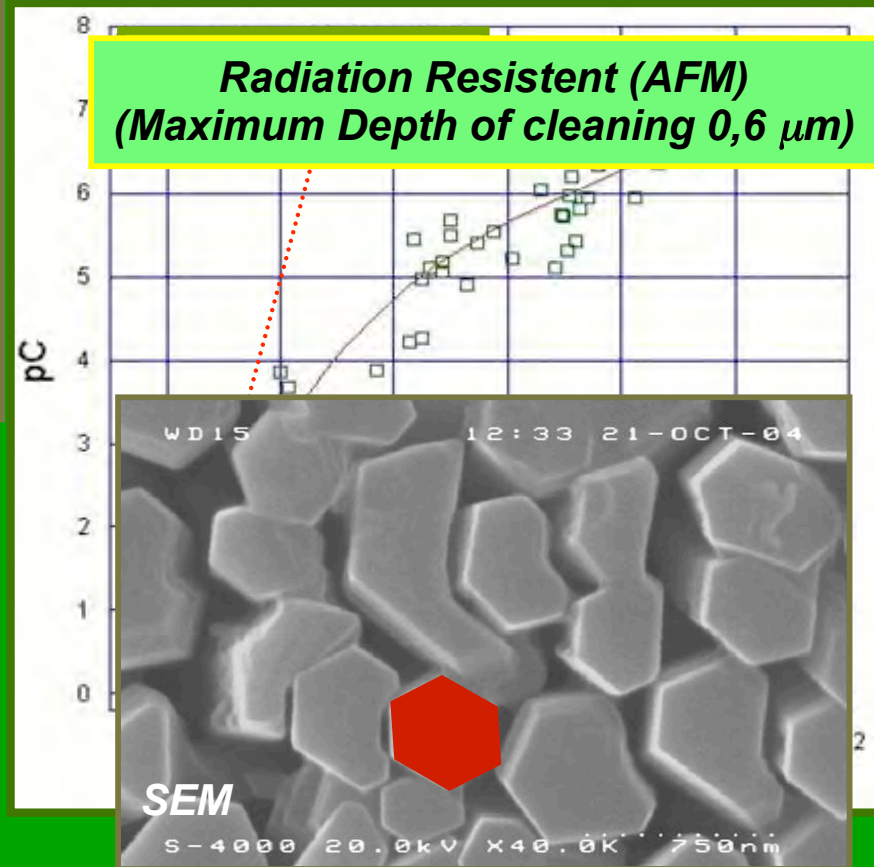
Structural Measurement



L
150

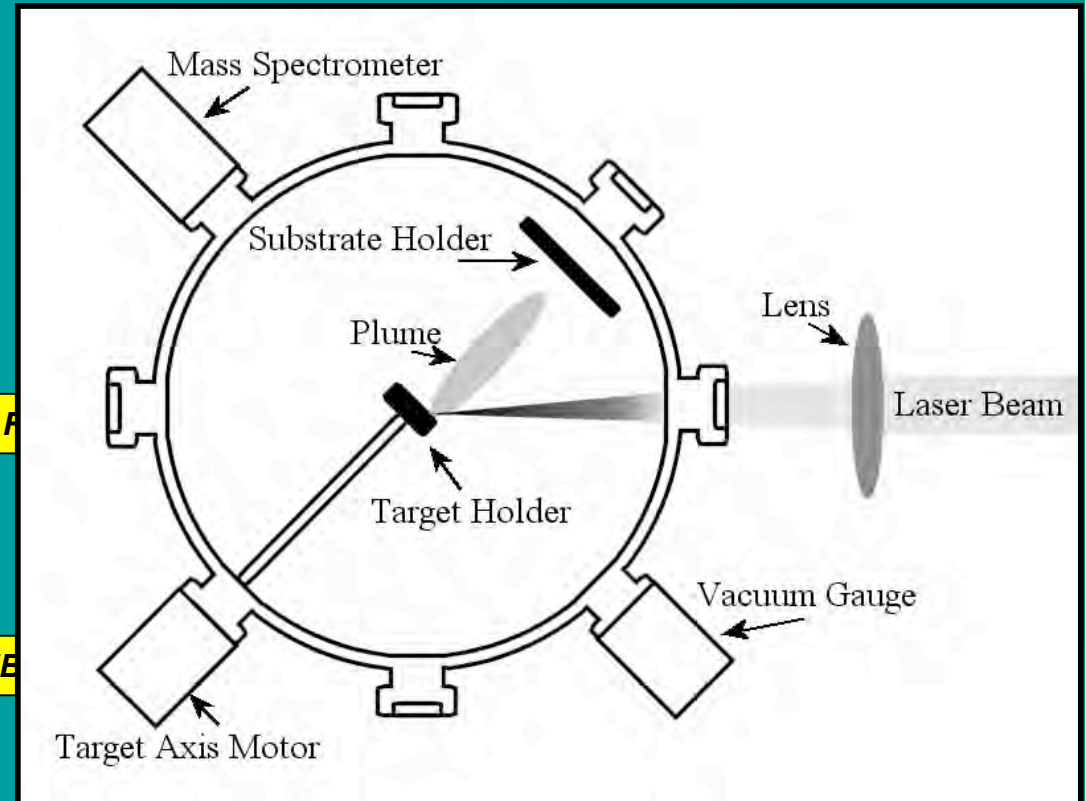
FINAL QE > 1X10⁻⁴

- Succ Well Defined Crystal Structure (Hexagon shape)
- Ext
- Easy QE recovery (Thick Film)



Radiation Resistant (AFM)
(Maximum Depth of cleaning 0,6 μ m)

- Xe Cl Laser (308 nm)
- τ_{pulse} 30 ns
- Incidence angle 45°
- UHV Chamber (better than 10^{-7} mbar)
- Online Mass Spectrometer
- Target Rotation Frequency 1Hz
- Up to 20J/cm² (0,6 GW/cm²) fluence
- Typical Target-Substrate Distance 5cm
- Typical Spot Size 1mm²



3. HIGH ENERGY PARTICLES IMPINGE ON THE SUBSTRATE

ADVANTAGES

- **HIGH FILM PURITY**
- **POSSIBILITY OF THICKNESS CONTROL (# PULSES)**
- **THIN PROTECTIVE FILMS POSSIBLE (TENS nm)**
- **MULTI LAYER DEPOSITION**
- **UNIFORM SURFACE**
- **GOOD ADHERENCE TO SUBSTRATE**

DRAWBACKS

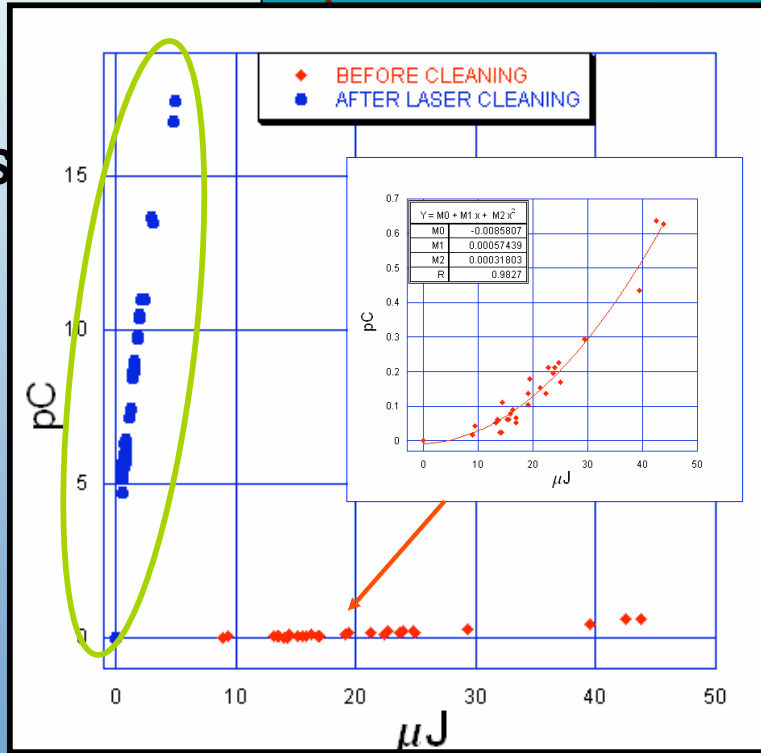
- **PRESENCE OF DROPLETS**
- **DIFFICULT LARGE THICKNESS**



IMPROVEMENTS

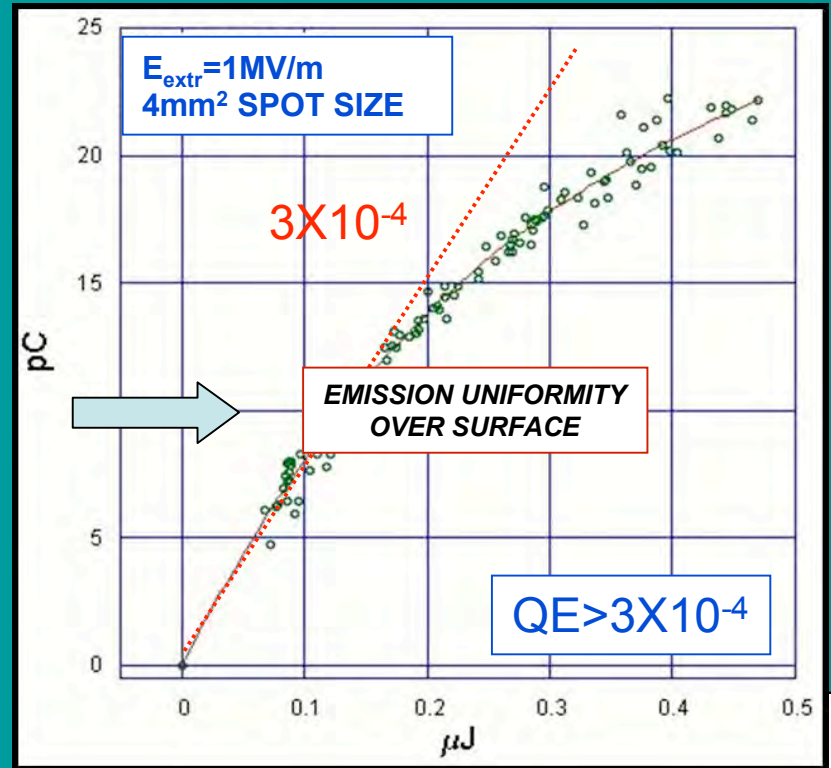
PLAD QE Measurements

STARTING WITH POOR QE QUADRATIC RESPONSE (C)
CLEANING OF 1mm² AREA WITH 5000 4GW/cm² PULSES



μm
nm
mm²
mbar
J/cm²
X10⁴
X10³
5cm

INVESTIGATE PLAD QE & LAYER PROTECTION



EMISSION UNIFORMITY OVER SURFACE

QE > 3X10⁻⁴

SAMPLE 2

SAME QE AS SPUTTERING

LASER SPOT SIZE	0,9 mm ²
FLUENCE	10 J/cm ²
# SHOTS FOR Mg	5X10 ⁴
TARGET DISTANCE	3,5cm

SEM : AMORPHOUS STRUCTURE OF FILM WITH DROPLETS
EDX : RESIDUAL C ON THE CLEANED AREA

PLAD RESULTS

SAMPLE 2

Mg FILM ON Si (100) SUBSTRATE
DEPOSITED WITH He CONFINMENT

STEP 1: CLEANING FIRST AREA
[1mm² WITH 1200 SHOTS AT 1,25GW/cm²]

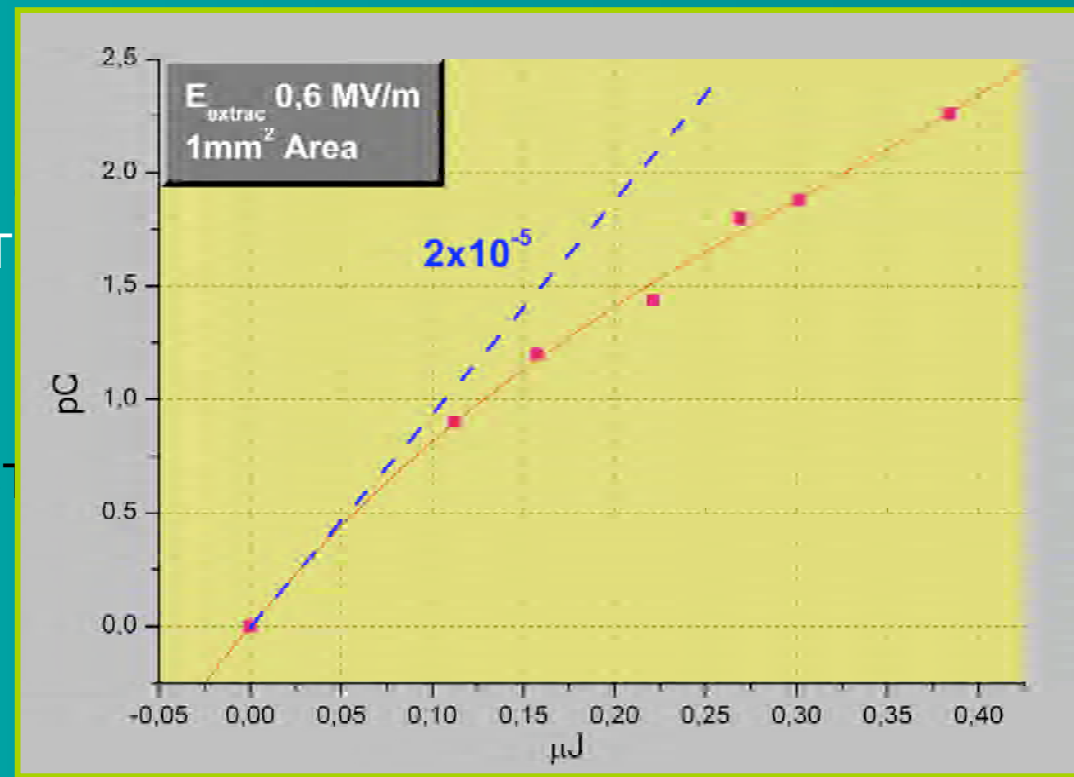
Mg THICKNESS	2,5 μm
He PRESSURE	5X10 ⁻² mbar
LASER SPOT SIZE	0,9 mm ²
LASER FLUENCE	10 J/cm ²
# SHOTS FOR Mg	5X10 ⁴
TARGET DISTANCE	3,5cm

STEP 2: QE MEASURING ON FIRST AREA

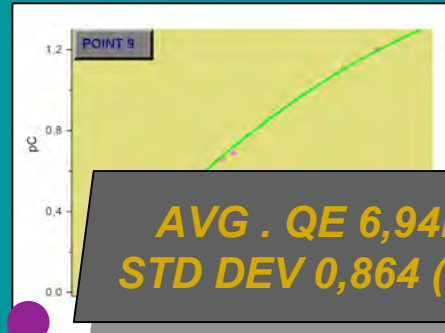
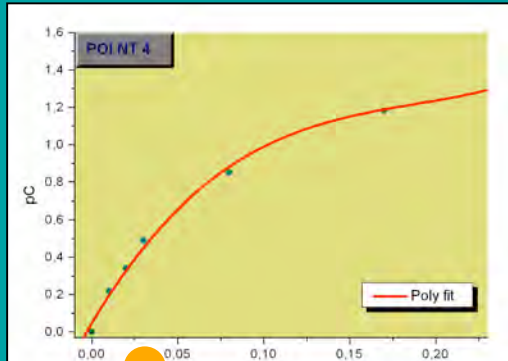
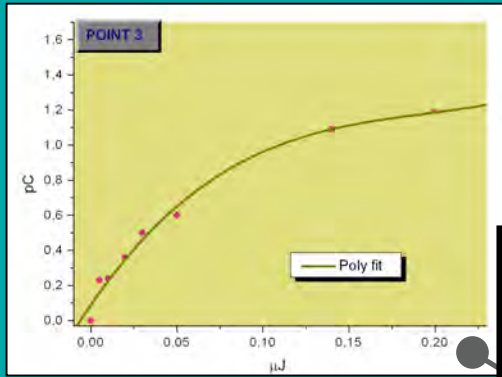
STEP 3: STRONG CLEANING
[0,5 mm² WITH 100 SHOTS AT

- Final QE 2x10⁻⁵
- Poor as expected

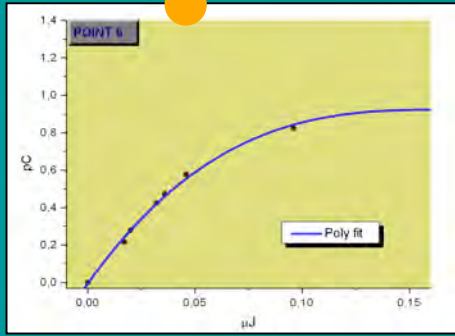
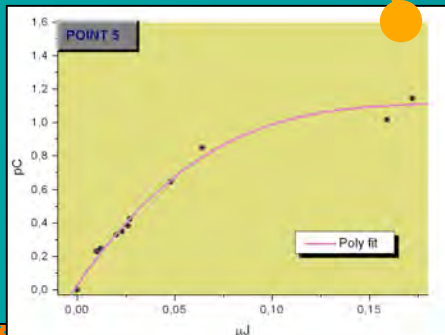
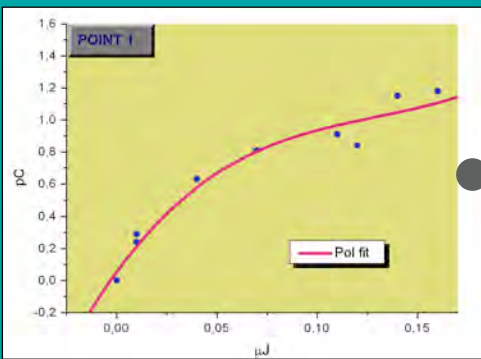
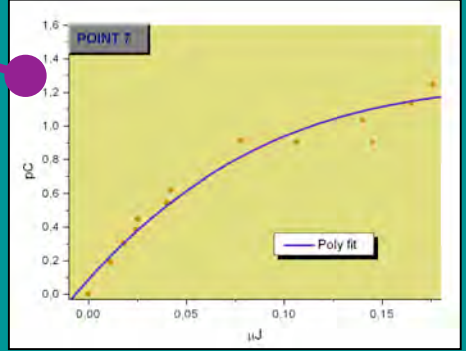
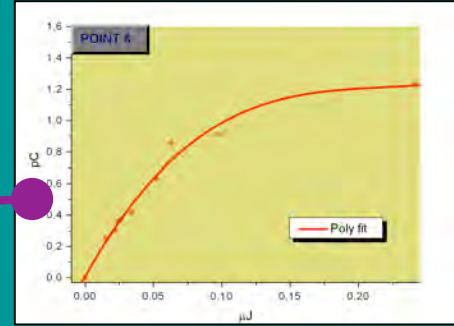
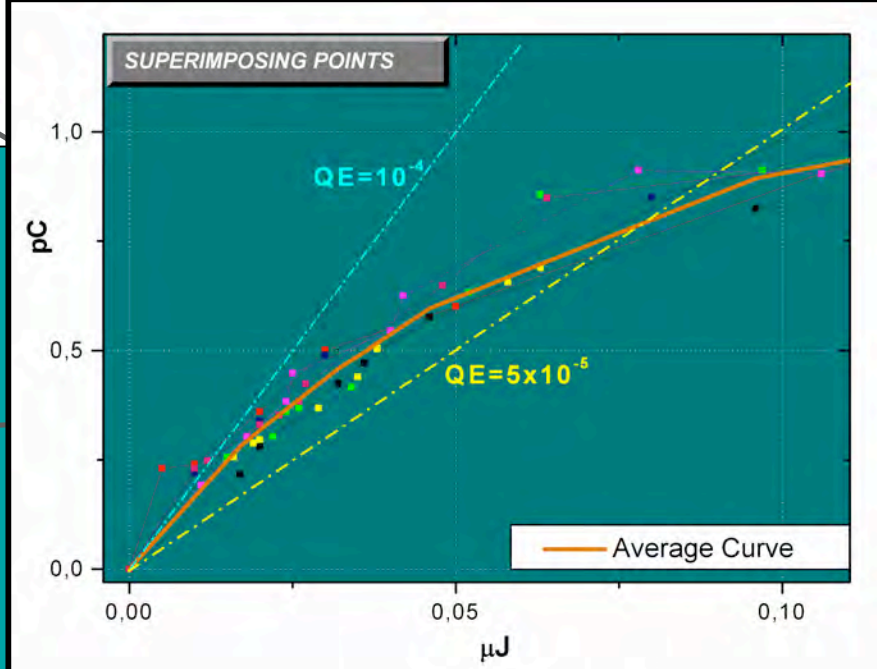
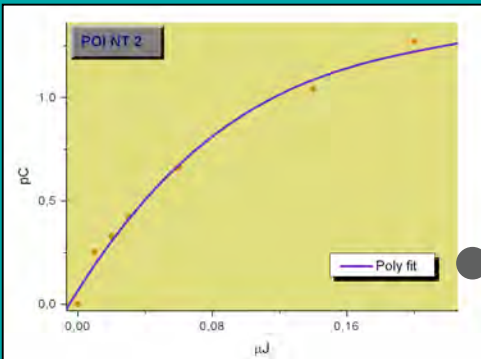
STEP 4: MEASURING QE DIS
[9 SUB-AREAS OF 0,04 mm²]



PLAD QE Uniformity



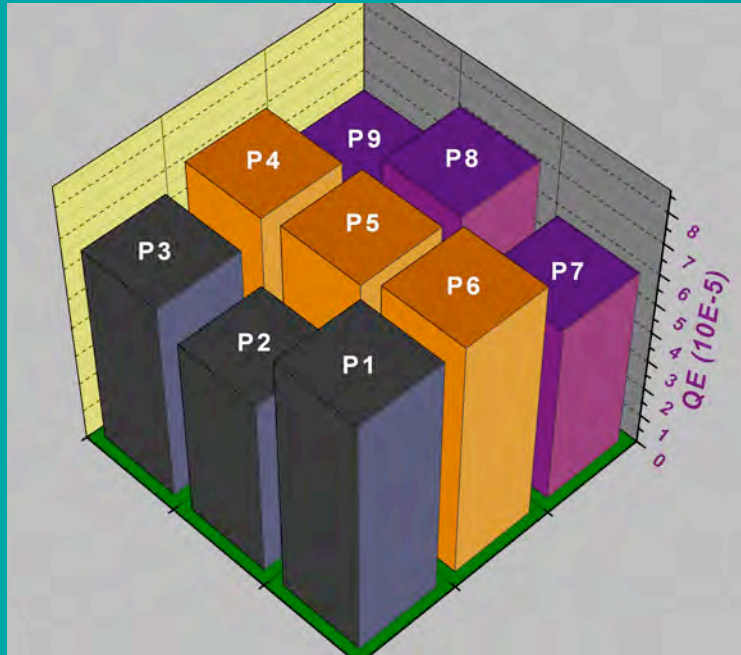
**AVG. QE 6,94E-5
STD DEV 0,864 (12%)**



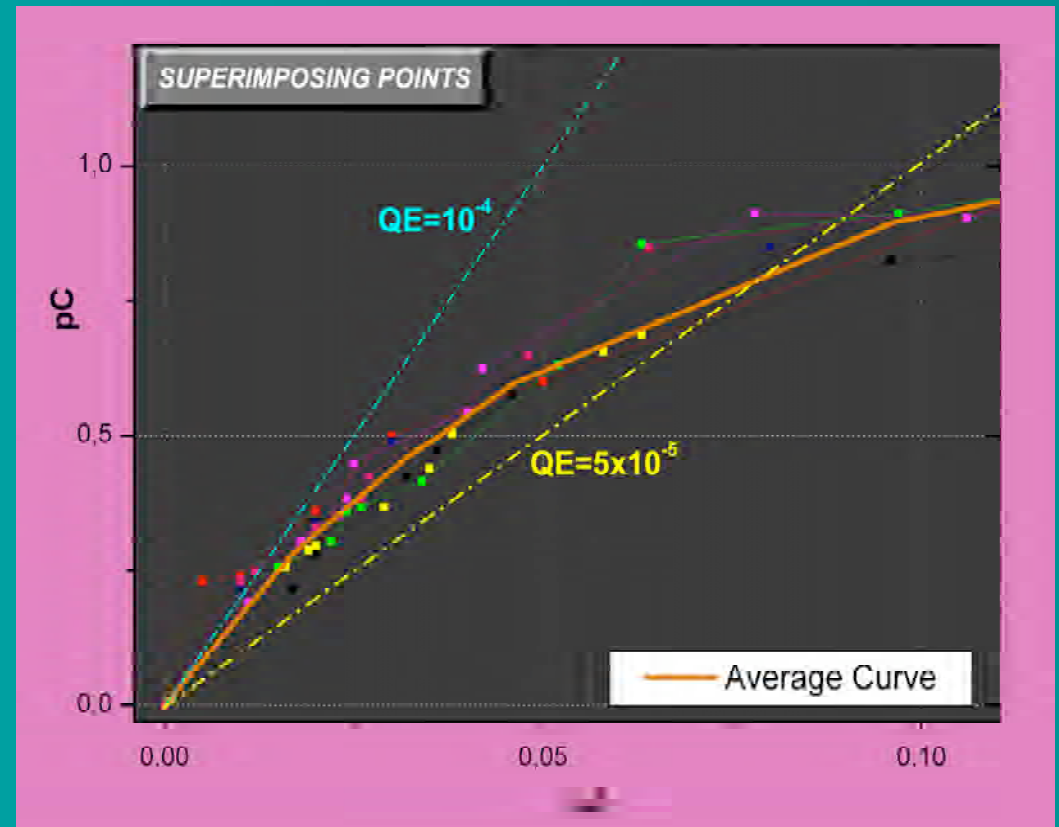
PLAD QE Uniformity

2nd AREA

MIN QE $5,76 \times 10^{-5}$
MAX QE $8,02 \times 10^{-5}$



AVG . QE $6,94 \times 10^{-5}$
STD DEV 0,864 (12%)



PLAD SEM

AMORPHOUS STRUCTURE WITH DROPLETS

1st AREA

LOW ENERGY CLEANING

2nd AREA

GRID DIFFRACTION PATTERN

MIDDLE ZONE FORMING CRYSTALS

HIGH ENERGY CLEANING

CRYSTAL STRUCTURE HEXAGON SHAPE

CONCLUSIONS

-PROTECTIVE LAYER WORKS BUT NOT NECESSARY WITH THICK FILMS

-THICK FILMS ARE FEASIBLE. IMPROVEMENT IN COURSE

-PROVEN QE = 3×10^{-4} IS SUFFICIENT BUT CAN BE IMPROVED



FUTURE PLANS

- IMPROVEMENT OF PLAD Mg
- DEPOSITION ON RF-GUN FLANGE
- ARC DEPOSITION
- INTEREST IN OTHER MATERIALS

